

**NONPROVISIONAL PATENT  
APPLICATION TRANSMITTAL RULE §1.53(b)  
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Customer No. 004372  
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Docket No. 025796-00014  
Date: December 15, 2003

Director of the U.S. PTO  
Washington, D.C. 20231

Sir:

Transmitted herewith for filing under 37 C.F.R. §1.53(b) is a nonprovisional patent application:

For (Title): HIGH-DENSITY MULTICHIP MODULE PACKAGE  
By (Inventors): Kwun Yao HO (Taiwan, Republic of Korea) and Moriss KUNG (Taiwan, Republic of Korea)

- ☒ 14 pages of Specification/Claims 1-24/Abstract are attached.
- ☒ Formal drawings (Fig(s). 1-7; 5 sheet(s)) is/are attached.
- ☒ A Declaration and Power of Attorney is attached.
- ☒ An assignment of the invention to VIA Technologies, Inc. is attached, along with Form PTO-1595 and a check for \$40.00.
- ☒ Priority of foreign application No. 091136733 filed December 19, 2003 in Republic of China is claimed under 35 U.S.C. §119.
- ☒ A certified copy of the above corresponding foreign application is attached.

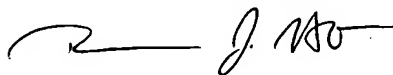
The filing fee is calculated below and includes claim status after entry of any Preliminary Amendment noted above:

FOR:	NO. FILED	NO. EXTRA
BASIC FEE		
TOTAL CLAIMS	24 - 20	= 4
INDEP CLAIMS	2 - 3	= 0
<input type="checkbox"/> MULTIPLE DEPENDENT CLAIMS		

SMALL ENTITY		OR	LARGE ENTITY	
RATE	FEE		RATE	FEE
	\$ 385	OR		\$ 770
x 9 =	\$	OR	x 18	\$ 72
x 43 =	\$	OR	x 86	\$ 0
+145 =	\$	OR	+290	\$
TOTAL	\$	OR	TOTAL	\$ 842

- ☒ A check in the amount of \$882 (\$842 for the filing fee and \$40 for the Assignment Recordation Fee) is attached. Please charge any fee deficiency or credit any overpayment to Deposit Account No. 01-2300.

Respectfully submitted,



Raymond J. Ho  
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RJH/rkc

